

INTERNATIONAL STANDARD

NORME INTERNATIONALE



**Printed boards and printed board assemblies – Design and use –
Part 6-4: Land pattern design – Generic requirements for dimensional drawings
of surface mounted components (SMD) from the viewpoint of land pattern
design**

**Cartes imprimées et cartes imprimées équipées – Conception et utilisation –
Partie 6-4: Conception de la zone de report – Exigences génériques pour les
dessins dimensionnels de composants montés en surface (CMS) du point
de vue de la conception de la zone de report**



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INTERNATIONAL ELECTROTECHNICAL COMMISSION

**PRINTED BOARDS AND PRINTED BOARD ASSEMBLIES –
DESIGN AND USE –**
**Part 6-4: Land pattern design – Generic requirements for dimensional
drawings of surface mounted components (SMD) from the viewpoint of
land pattern design**

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The text of this International Standard is based on the following documents:

FDIS	Report on voting
91/1561/FDIS	91/1572/RVD

Full information on the voting for the approval of this International Standard can be found in the report on voting indicated in the above table.

This document has been drafted in accordance with the ISO/IEC Directives, Part 2.

A list of all parts in the IEC 61188 series, published under the general title *Printed boards and printed board assemblies – Design and use*, can be found on the IEC website.

The committee has decided that the contents of this document will remain unchanged until the stability date indicated on the IEC website under "<http://webstore.iec.ch>" in the data related to the specific document. At this date, the document will be

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PRINTED BOARDS AND PRINTED BOARD ASSEMBLIES – DESIGN AND USE –

Part 6-4: Land pattern design – Generic requirements for dimensional drawings of surface mounted components (SMD) from the viewpoint of land pattern design

1 Scope

This part of IEC 61188 specifies generic requirements for dimensional drawings of SMD from the viewpoint of land pattern design.

The purpose of this document is to prevent land pattern design issues caused by lack of information and/or misuse of the information from SMD outline drawing as well as to improve the utilization of IEC 61188 series.

This document is applicable to the SMD of semiconductor devices and electrical components.

2 Normative references

The following documents are referred to in the text in such a way that some or all of their content constitutes requirements of this document. For dated references, only the edition cited applies. For undated references, the latest edition of the referenced document (including any amendments) applies.

IEC 60194, *Printed board design, manufacture and assembly – Terms and definitions*

IEC 60194-2, *Printed board design, manufacture and assembly – Vocabulary – Part 2: Common usage in electronic technologies as well as printed board and electronic assembly technologies*

3 Terms, definitions and symbols

For the purposes of this document, the terms and definitions given in IEC 60194 and IEC 60194-2 apply, and the reference symbols are shown in Table 1.

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